SFH 4441

MIDLED® Mini

Narrow beam LED in Mini MIDLED package (940 nm)





Applications

Remote Control, Proximity, Ambient Light Sensing

Features:

- Package: clear silicone
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- Highly Efficient Infrared LED
- Short switching times
- Narrow halfangle (± 17°)
- Low profile component

Ordering Information

Туре	Radiant intensity 1)	Radiant intensity 1) typ.	Ordering Code
	$I_{\rm F} = 100 \text{ mA}; t_{\rm p} = 20 \text{ ms}$ $I_{\rm e}$	$I_{\rm F} = 100 \text{ mA}; t_{\rm p} = 20 \text{ ms}$ $I_{\rm e}$	
SFH 4441	25 200 mW/sr	65 mW/sr	Q65111A4266



Mayi	DOLLIDO.	Pati	nac
IVIAXI	mum	Nau	IIU5

Τ.	=	25	$^{\circ}C$	

Parameter	Symbol		Values
Operating temperature	T _{op}	min.	-40 °C
	op	max.	85 °C
Storage temperature	T _{stg}	min.	-40 °C
	3.9	max.	85 °C
Reverse voltage 2)	V_R	max.	12 V
Forward current	I _F	max.	100 mA
Surge current $t_p \le 300 \ \mu s; \ D = 0$	I _{FSM}	max.	1 A
Power consumption	P _{tot}	max.	180 mW
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}	max.	2 kV



Characteristics

 $I_{_{\rm F}}$ = 100 mA; $t_{_{
m p}}$ = 20 ms; $T_{_{
m A}}$ = 25 °C

Parameter	Symbol		Values
Peak wavelength	λ_{peak}	typ.	950 nm
Centroid wavelength	$\lambda_{ m centroid}$	typ.	940 nm
Spectral bandwidth at 50% I _{rel,max}	Δλ	typ.	42 nm
Half angle	φ	typ.	17 °
Dimensions of active chip area	L×W	typ.	0.3 x 0.3 mm x mm
Rise time (10% / 90%) $I_F = 100 \text{ mA}; R_L = 50 \Omega$	t _r	typ.	12 ns
Fall time (10% / 90%) $I_F = 100 \text{ mA}; R_L = 50 \Omega$	t _f	typ.	12 ns
Forward voltage	V_{F}	typ. max.	1.5 V 1.8 V
Forward voltage $I_F = 1 \text{ A}; t_p = 100 \mu\text{s}$	V_{F}	typ. max.	2.3 V 3 V
Reverse current $^{2)}$ $V_R = 5 V$	I _R	max. typ.	10 μA 0.01 μA
Total radiant flux 3)	Фе	typ.	50 mW
Radiant intensity ¹⁾ $I_F = 1 \text{ A}; t_p = 25 \mu \text{s}$	l _e	typ.	490 mW/sr
Temperature coefficient of brightness	TC,	typ.	-0.5 % / K
Temperature coefficient of voltage	TC _v	typ.	-1.3 mV / K
Temperature coefficient of wavelength	$TC_{_{\lambda}}$	typ.	0.3 nm / K
Thermal resistance junction ambient real 4)	R_{thJA}	max.	400 K / W
Thermal resistance junction solder point real 5)	R_{thJS}	max.	200 K / W



Brightness Groups

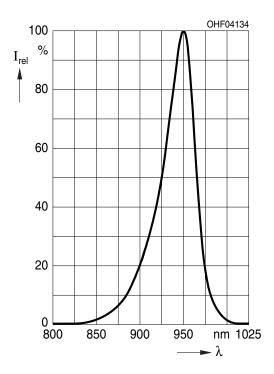
 $T_A = 25$ °C

Group	Radiant intensity $I_F = 100 \text{ mA}$; $t_p = 20 \text{ ms}$ min. I_e	Radiant intensity $I_F = 100 \text{ mA}$; $t_p = 20 \text{ ms}$ max. I_e	
Т	25 mW/sr	50 mW/sr	
U	40 mW/sr	80 mW/sr	
V	63 mW/sr	125 mW/sr	
AW	100 mW/sr	200 mW/sr	

Only one group in one packing unit (variation lower 2:1).

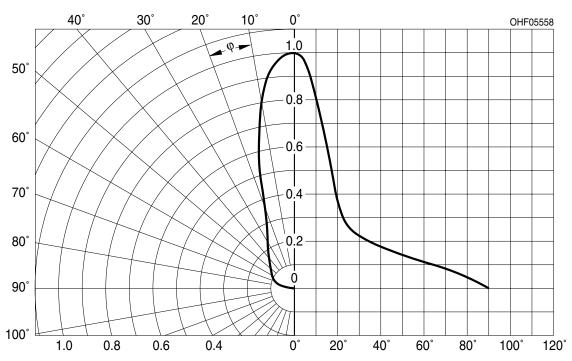
Relative Spectral Emission 6), 7)

$$I_{rel} = f(\lambda); I_F = 100 \text{ mA}; t_p = 20 \text{ ms}$$



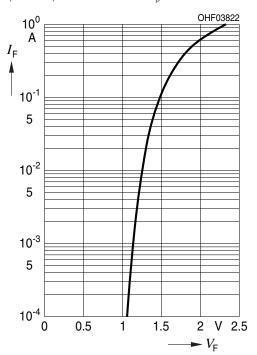
Radiation Characteristics 6), 7)





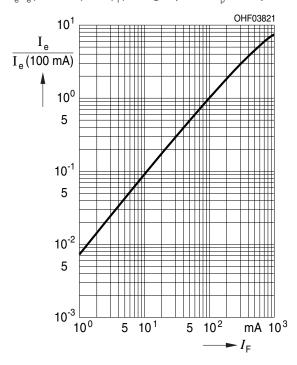
Forward current 6), 7)

 $I_F = f(V_F)$; single pulse; $t_D = 100 \mu s$



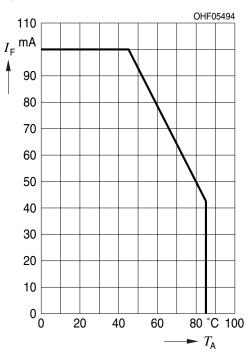
Relative Radiant Intensity 6), 7)

 $I_e/I_e(100 mA) = f(I_F)$; single pulse; $t_p = 25 \mu s$



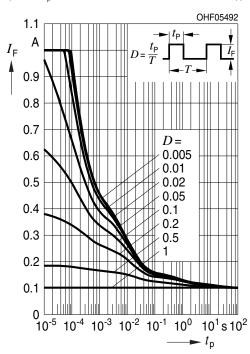
Max. Permissible Forward Current

$$I_{F,max} = f(T_A); R_{thJA} = 400 K/W$$



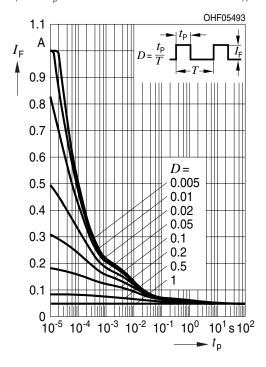
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; duty cycle D = parameter; $T_A = 25$ °C

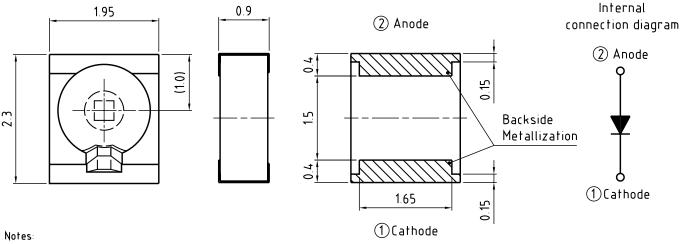


Permissible Pulse Handling Capability

 $I_F = f(t_p)$; duty cycle D = parameter; $T_A = 85$ °C



Dimensional Drawing 8)



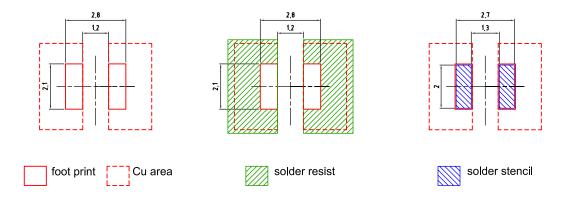
1. Unspecified tolerance shall be ±0.15

2. Dimension in parenthesis are shown for reference

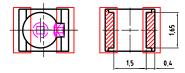
C67062-A0032-A1-05

Approximate Weight: 10.0 mg

Recommended Solder Pad 8)



Component Location on Pad

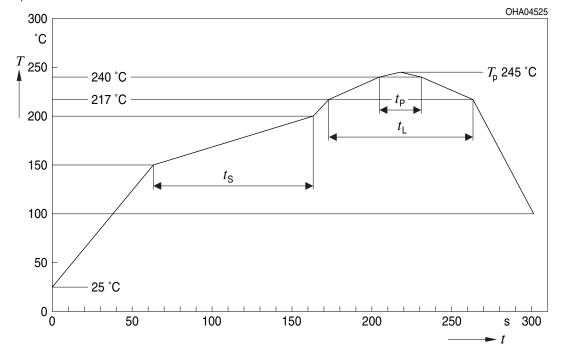


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The package is casted with silicone. Mechanical stress at the surface of the unit should be avoided.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

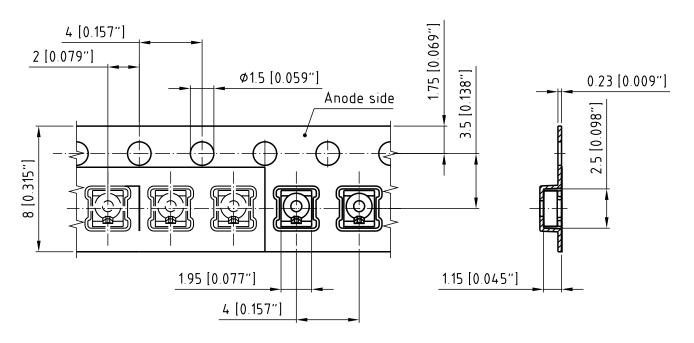


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Profile Feature	Symbol	Pb	-Free (SnAgCu) Ass	sembly	Unit
	,	Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t _s T _{Smin} to T _{Smax}	t _s	60	100	120	S
Ramp-up rate to peak*) T_{Smax} to T_{P}			2	3	K/s
Liquidus temperature	T_{L}		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T _P - 5 K	t _P	10	20	30	S
Ramp-down rate* T _p to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component

Taping 8)

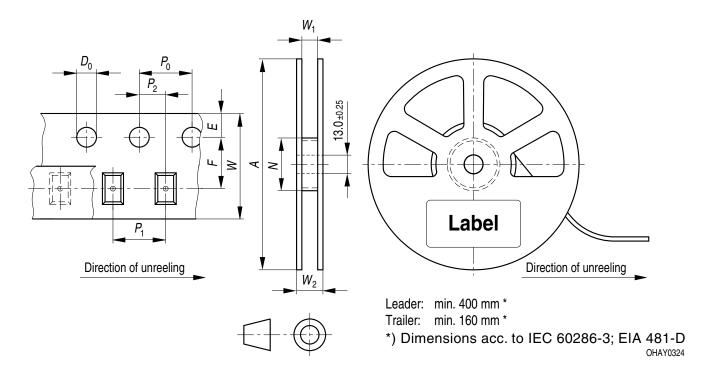


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^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Tape and Reel 9)



Reel dimensions [mm]

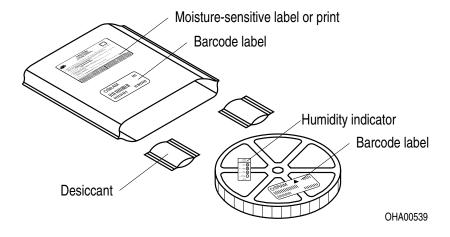
Α	W	N_{min}	W_1	$W_{2 \text{ max}}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1	60	8.4 + 2	14.4	3000



Barcode-Product-Label (BPL)



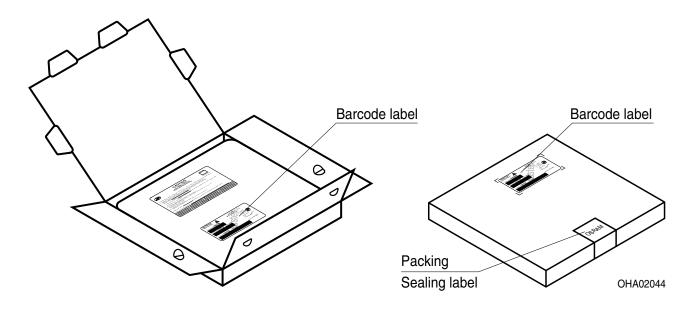
Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Transportation Packing and Materials 8)



Dimensions of transportation box in mm

Width	Length	Height
200 ± 5 mm	195 ± 5 mm	30 ± 5 mm



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the LED specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. As is also true when viewing other bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

For further application related informations please visit www.osram-os.com/appnotes



Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

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For information on the types in question please contact our Sales Organization.

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Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

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Glossary

- Radiant intensity: Measured at a solid angle of $\Omega = 0.01 \text{ sr}$
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- Total radiant flux: Measured with integrating sphere.
- Thermal resistance: junction ambient, mounted on PC-board (FR4), padsize 16 mm² each
- Thermal resistance: junction soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- Typical Values: Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Testing temperature: $T_A = 25^{\circ}C$
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ⁹⁾ **Tape and Reel**: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



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